METHOD OF REMOVING PARTICLES FROM STAGE AND CLEANING PLATE

ABSTRACT OF THE DISCLOSURE

Disclosed is a method of readily removing particles from a stage, that is, a stage particle removing method for removing particles from a stage that holds a planar workpiece. A resin film is placed on the stage, and collected from the stage. The resin film is coated over at least one surface of the planar workpiece such as a semiconductor wafer or glass substrate. The resin film is brought into contact with the stage. The resin film may not be coated over the planar workpiece itself but may be coated over a dedicated planar piece shaped similarly to the planar workpiece, for example, a thin metallic plate that is very smooth. The used resin film is peeled off from the planar workpiece or dedicated planar piece, and the resin film is coated again. Thus, the planar workpiece or dedicated planar piece can be reused.

(Figure 8)